Presentation Disclaimer

The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.

MPI Divisions

Probe Card

Photonics Automation

Advanced Semiconductor Test

Thermal Test

Celadon Systems

MPI Global Presence

MPI Locations

Worldwide

MPI America
CA, USA (2017)

MPI Suzhou
Jiangsu, CN (2017)

Celadon Systems
MN, USA (2021)

Taiwan

Headquarters
Hsinchu, TW (2000)

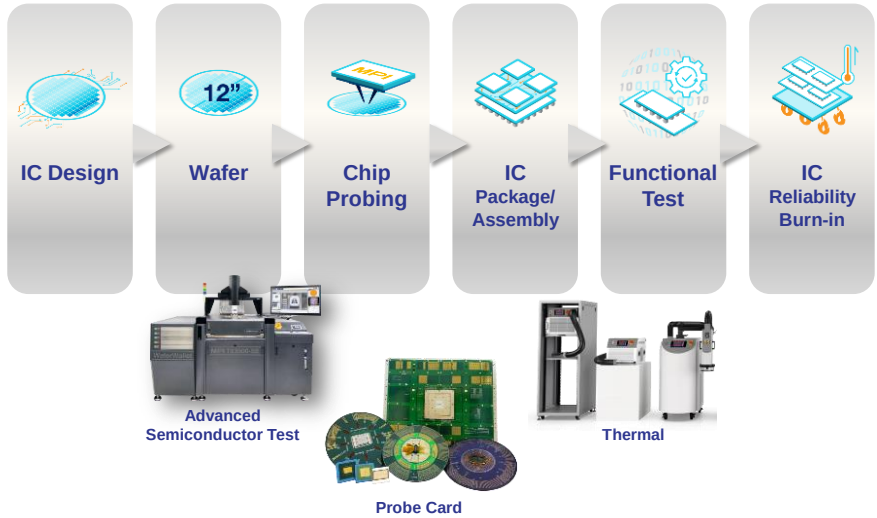
Luzhu Office
Kaohsiung, TW (2006)

2nd Production Site
Hsinchu, TW (2012)

Xinpu Office
Hsinchu, TW (2014)

3rd Production Site
Hsinchu, TW (2021)

Supply Chain Infographic



Agenda

Business Contents

Probe Card

Photonics Automation

Thermal & AST

Financial Statements

MPI CORPORATION

Probe Card

READY FOR THE TEST™

7

MPI Probe Card

Advanced Wafer Sort Test Solutions

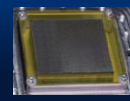
Vertical / MEMS Probe Card

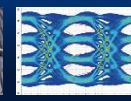
Cantilever Probe Card

Features


Fine Pitch


MEMS


High Pin Count


High Speed

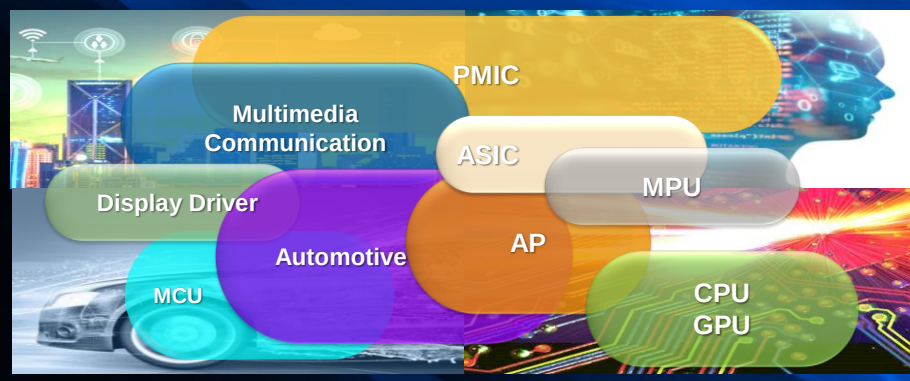

Substrate


Hand-wired

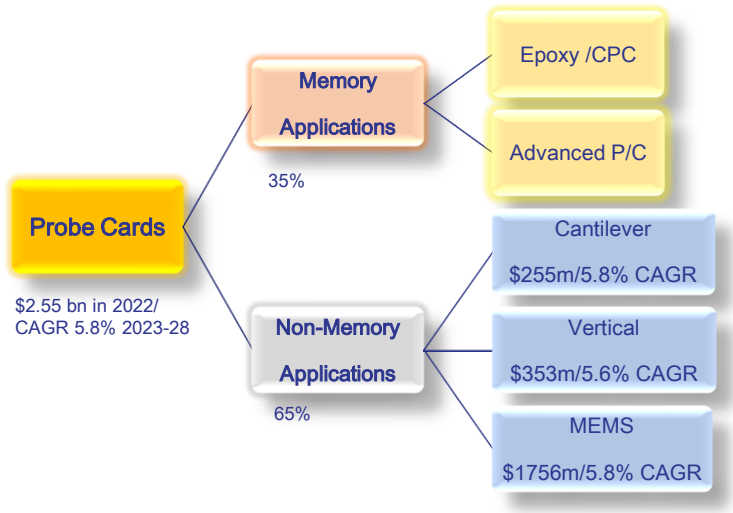

RF

MPI Probe Card

Full range of products for the applications
sufficient coverage solutions to IC markets



Global Probe Card Market Update

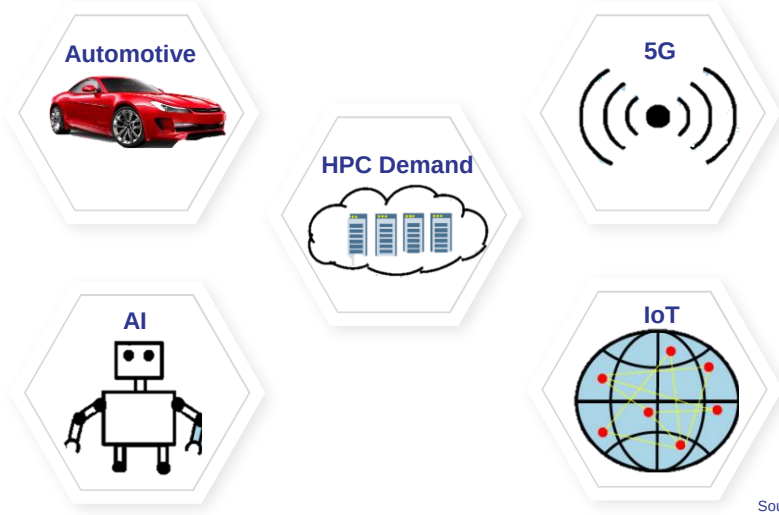


Top 10 Probe Card Vendors (2017-2022)

(Rank)	2017	2018	2019	2020	2021	2022
FormFactor, Inc. (USA)	1	1	1	1	1	1
Micronics Japan Co., Ltd. (Japan)	2	3	3	3	3	3
Technoprobe (Italy)	3	2	2	2	2	2
Japan Electronic Materials (Japan)	4	4	4	4	4	4
MPI Corporation (Taiwan)	5	5	5	5	5	5
SV TCL (Singapore)	6	6	6	7	8	7
Microfriend (Korea)	7	10	10	10	-	-
Korea Instrument (Korea)	8	7	8	6	7	6
Cascade Microtech (USA)	-	-	-	-	-	-
FEINMETALL (Germany)	11	12	11	14	-	-

HPC Demand

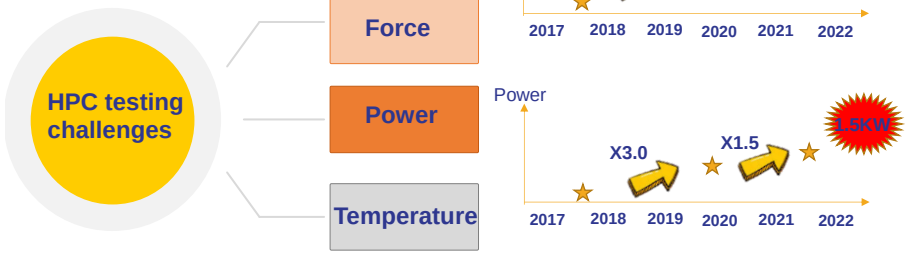
The demand of HPC (High Performance Computing) growth rapidly.



Source: TSMC

HPC Challenges

High Force, High Power, and High Temperature are the challenges for HPC testing.



3rd Annual SWTest Asia | Taiwan, October 27-28, 2022

Source: TSMC

Interface Technical Complexity Check in

Complexity Trends are on pace to be at 2022 targets(1 Cycle) or in some cases beyond

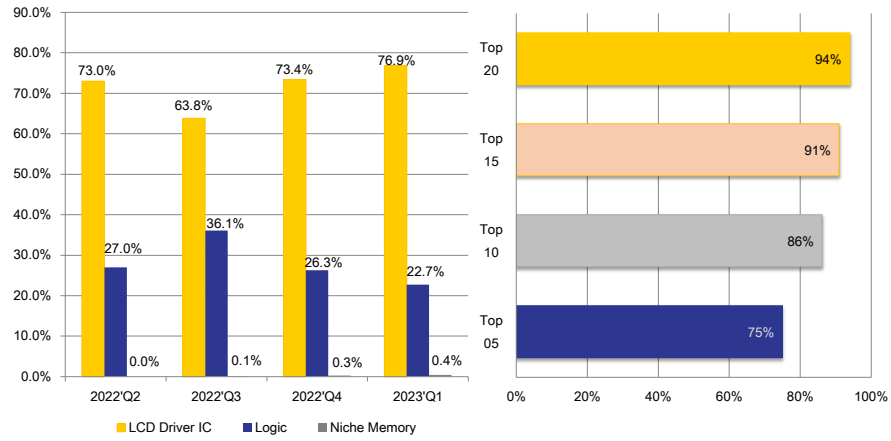
"2x4 Scaling"=2xPins, 2xPerformance, every 4 years

		2018	2022	2026
		Level 4	Level 5	Level 6
Pin Density	Pin Pitch	90um	70um	50um
	Total Contact Force	80kg	150kg	250kg
I/O Speed	Digital	32Gpbs	64Gpbs	128Gpbs
	RF/mmWave	< 12 GHz	29 GHz	+60 GHz
Device Power	Main Power	900 mV	750mV	625mV
	Single Rail	35A	50A	100A
	Impedance	2.2 mOhm	1.4 mOhm	0.8 mOhm
Thermal	Self Heating	75 W		
	Operating Range	0 to +80C	0 to +105C	-20 to +125C
Most Expensive Probe Card		$400K*	>$500K	>$700K

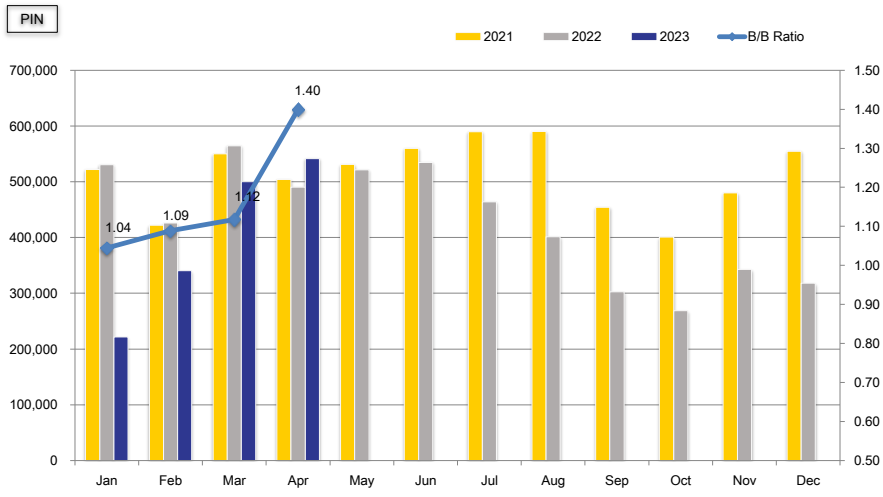
Source:Teradyne

Source:VLSI Research

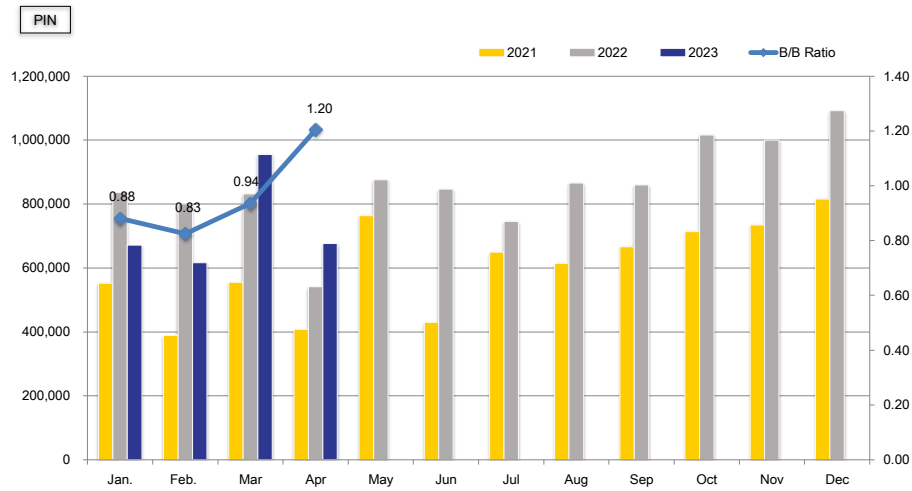
Product Mix of CPC (Cantilever)



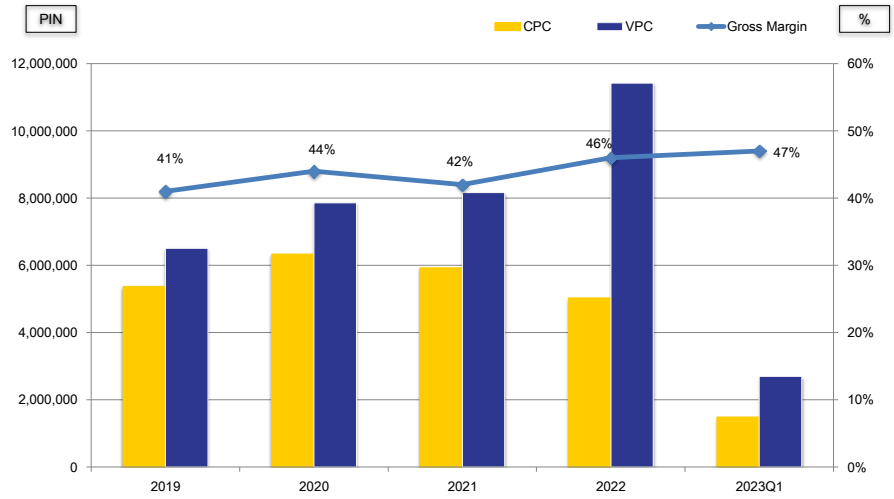
CPC Pin-Shipment_2023



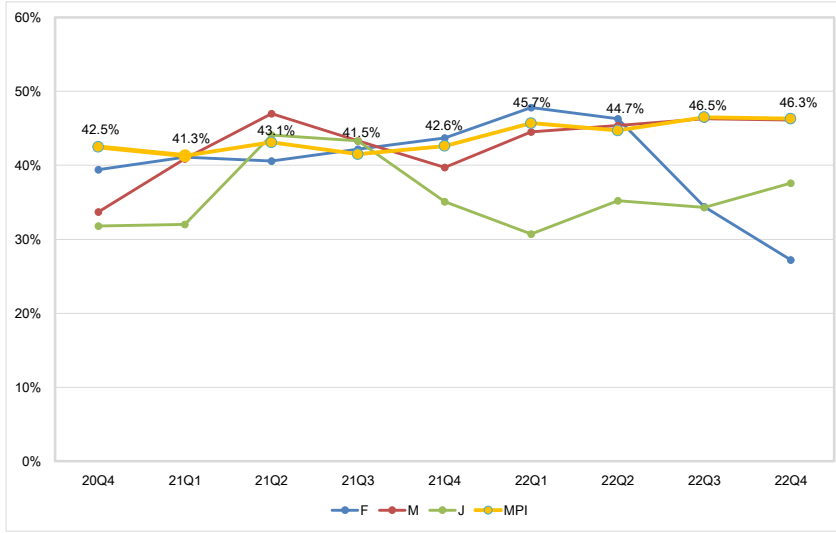
VPC Pin-Shipment_2023



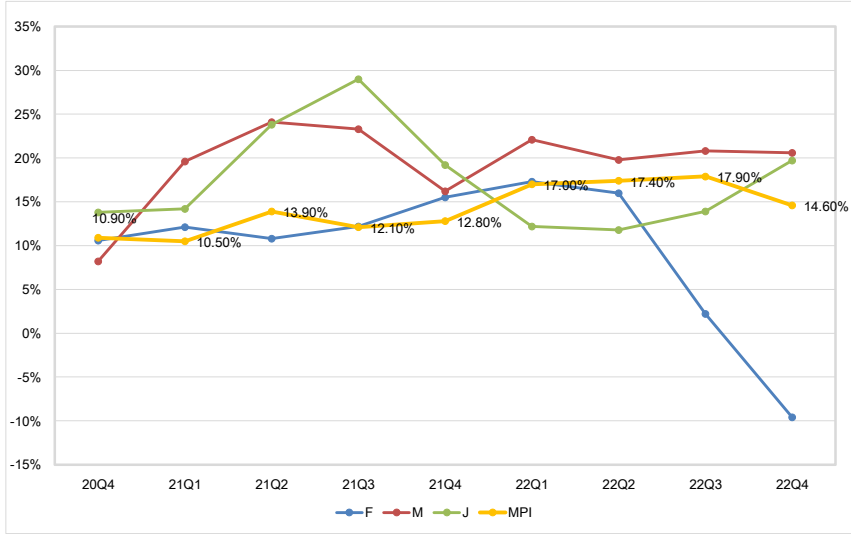
CPC and VPC Yearly Status



Gross Margin Between Global Peers



Operating Margin Between Global Peers



MPI Probe Card

Our Customer

The MPI is committing more than 800 customers globally to contribute to industrial development as well as providing testing industry advanced technology needs.

MPI CORPORATION

Photonics Automation

Product Portfolio and Capability

- **High Power VCSEL Wafer Testing**
  Wafer / Board Prober Development
  Testing methodology Development
- **High Power VCSEL PKG Testing**
  PKG Handler Development
  Testing methodology Development
- **VCSEL / Photo-Detector Testing**
  Wafer / Board Prober Development
  Testing methodology Development
- **RF Character**
  Wafer Level RF Testing Integration
- **SiPh Die/PKG Platform**
  SiPh Handler Development
- **uLED Mass Production Methodology**
  Wafer prober for large quantity die testing method
- **Panel testing platform development**
  Panel / Panel in-process testing platform

Development Plan by Application

Optical Sensing	Optical Communications	Micro Display
➢ Focus on Sensing VCSEL Testing ➢ Production Wafer Prober in Low Temperature ➢ High Power Measurement Tool and Technology Development ➢ Flip Chip Wafer VCSEL testing Solution ➢ Package / Hybrid Device testing tool	➢ Focus on VCSEL/Photodetector Testing ➢ Wafer Prober for Dark / Responsivity / Capacity measurement ➢ RF Measurement Capability Development ➢ SiPh package testing approaching	➢ Lab and production wafer testing tool development ➢ Contacting Accuracy Improvement ➢ Innovative testing methodology ➢ Optical measurement in production methodology

MPI CORPORATION

Thermal/AST

READY FOR THE TEST™

MPI Thermal

Hot and Cold Air Flow
Environmental Temperature Test

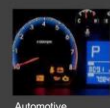
-100°C +300°C

ThermalAir Series

Temperature Testing Systems

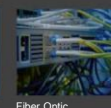
Applications & Industry Segments


Semiconductor

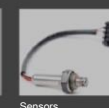

Automotive


Aerospace


Telecommunications


Fiber Optic


Electronics


Sensors


Advanced Technology

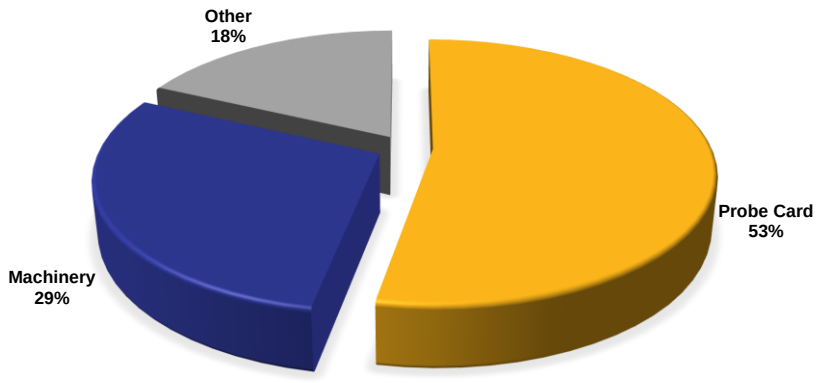
MPI's Ideation

- To Combine Two Very Unique Values
- The MPI Corporation
  - Operational Excellence – High quality, on time
  - Production Test Experience – 24/7 systems reliability
  - Customer Centric – Highest value without compromise
- Management & Market Expertise
  - More than 50 years together in Device Modeling, RF & mmW, WLR, High-Power, Failure Analysis, Thermal solutions...
  - Visionary and Innovative Ideas
  - Worldwide Partner Relationships

MPI CORPORATION

Financial Statements

1Q23 Shipment Breakdown



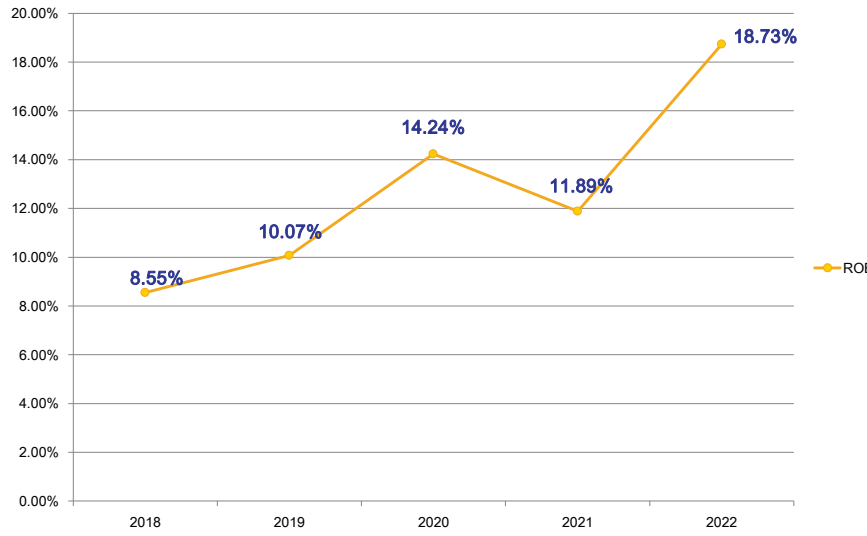
Solid Performance

Continuous revenue growth driven by high customer satisfaction

Margin expansion is the result of strong RD investment

Accelerating profit earning shows MPI's shareholder commitment

ROE



Balance Sheet Highlight

NT$Million	2023' 1Q		2022' 1Q	
Cash and Cash Equivalents	2,385	22%	1,307	13%
Fixed Assets	4,481	41%	4,408	44%
Total Assets	10,959	100%	10,035	100%
LT Debt	996	9%	1,113	11%
Shareholders' Equity	7,204	66%	6,376	64%
EBITDA	333	18%	366	21%

*EBITDA=operating income + depreciation & amortization expenses

Income Statement

NT$Million	1Q2023		1Q2022	
Net Sales	1,783,537	100%	1,720,155	100%
Cost of Goods Sold	939,346	53%	934,315	54%
Gross Profit	844,191	47%	785,840	46%
Operating Expense	517,648	29%	492,651	29%
Operating Income	326,543	18%	293,189	17%
Investment Income & Others	6,864		73,674	
Net Income (before tax)	279,721	15%	306,230	18%
EPS	2.98		3.25	


MPI CORPORATION
Thank You
http://www.mpi-corporation.com
READY FOR THE TEST™